

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"5059630".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 09:38
L2	1	1 and (semiconductor chip die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 09:38
L3	652	(molding near1 (resin compound)) with (pores porous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 09:40
L4	54	3 and (wafer chip semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 09:52
L5	1	"5904502".pn. and (pore porous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 10:03
L6	30707	(wafer die dice) same (substrate carrier board) same ((dielectric insulating insulation) near1 (film layer material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 10:22
L7	832	6 and (((dielectric insulating insulation) near1 (film layer material)) near4 (pore porous))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 10:21
L8	224	7 and ((wafer die dice) with (singulat\$3 cut\$4 separat\$3 dicing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 13:43

## EAST Search History

L9	149	7 and ((wafer die dice) near4 (singulat\$3 cut\$4 separat\$3 dicing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 10:24
L10	41	7 and ((wafer die dice) with (singulat\$3 cut\$4 dicing)) and (passive capacitor resistor inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 13:44